

HSF

NOTES:

Current Rating: 3.0AMP
 Contact Resistance: 35mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 500MΩ Min
 Operation Temperature: -40°C to +105°C

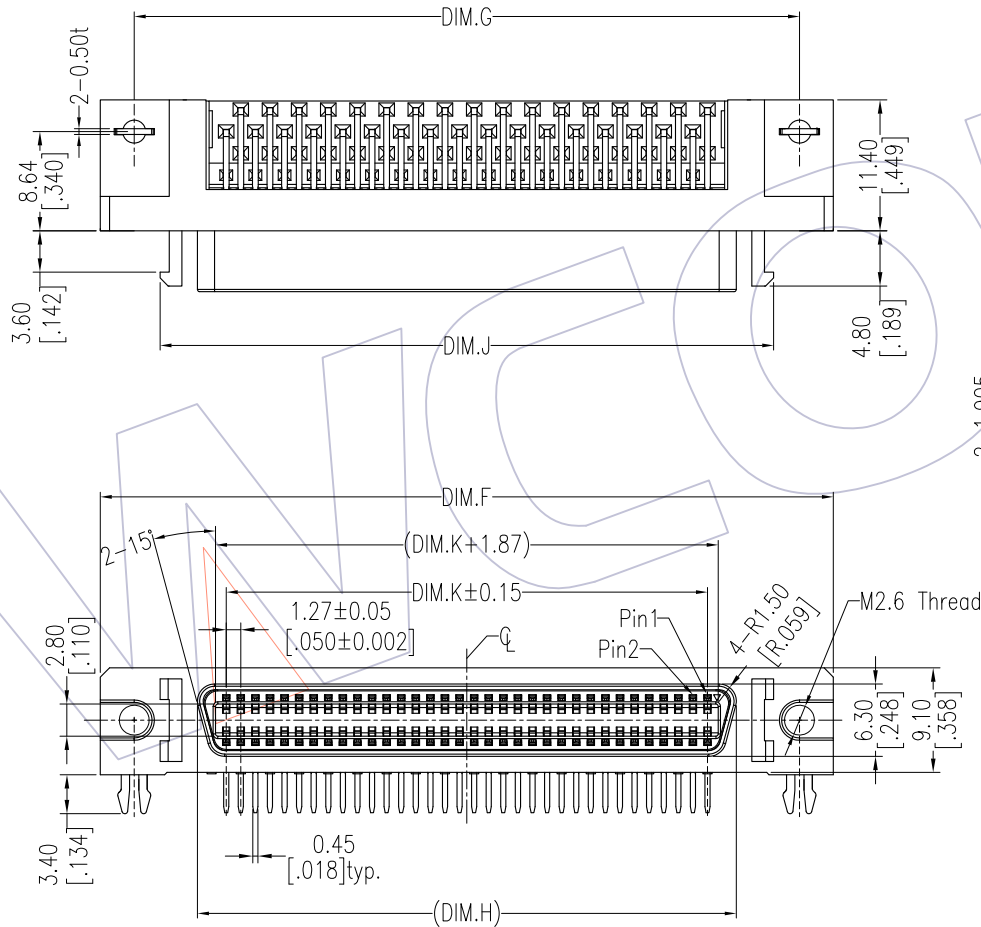
Contact Material: Phosphor Bronze
 Contact Plating: Au and Sn over Ni
 Shell Material: Zinc Alloy
 Shell Plating: Ni 100u"
 Fixing Material: Phosphor Bronze
 Fixing Plating: Sn over Ni
 Housing Material: PBT+30%G.F(UL94V-0)
 Cover Material: PBT+30%G.F(UL94V-0)

Ordering Information

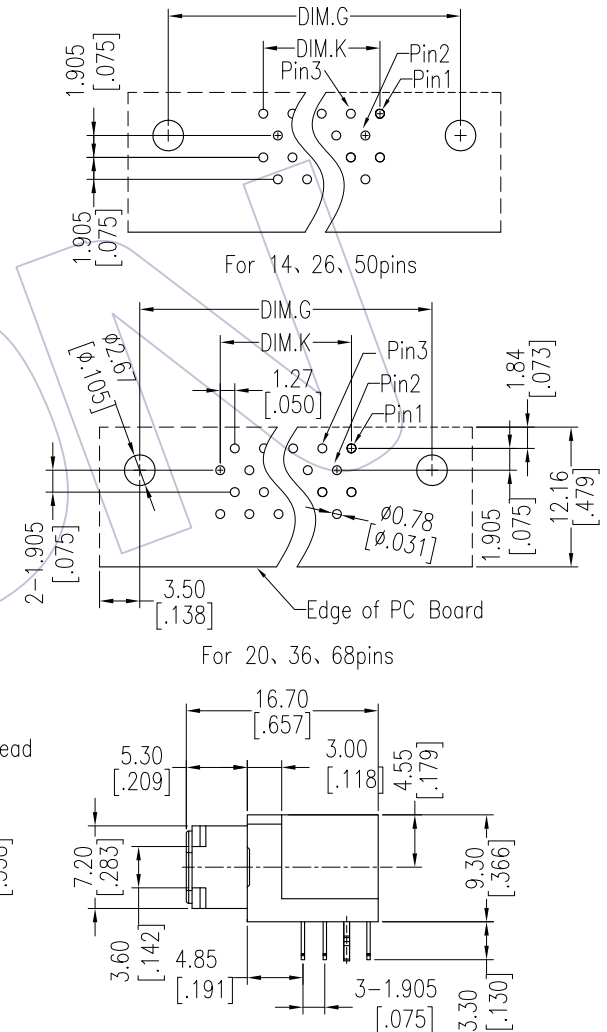
6321-0 XX R D SX M W A 02

No. of Pins	Contact Plating	A=Tray
14P 36P	S1=3u"Gold/Tin	
20P 50P	S3=10u"Gold/Tin	
26P 68P	S4=15u"Gold/Tin	
	S5=30u"Gold/Tin	

53.43	41.91	46.83	57.93	63.83	68
42.00	30.48	35.40	46.50	52.40	50
33.11	21.59	26.51	37.61	43.51	36
26.76	15.24	20.16	31.26	37.16	26
22.95	11.43	16.35	27.45	33.35	20
19.14	7.62	12.54	23.64	29.54	14
DIM.J	DIM.K	DIM.H	DIM.G	DIM.F	PIN数



Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)



		OPERATION		DRAW	DATE	SCALE	FIT	PART NO.
		x.x	±0.40					
A1	2013/08/28	Modify DIM.H		CHECK	DATE	SIZE	A4	TITLE:
A0	2013/08/20	NEW						Angle
REV	DATE	MODIFICATION DESCRIPTION		APPROVE	DATE	PROJ.	☞	Customer NO.
		DIM	TOL					